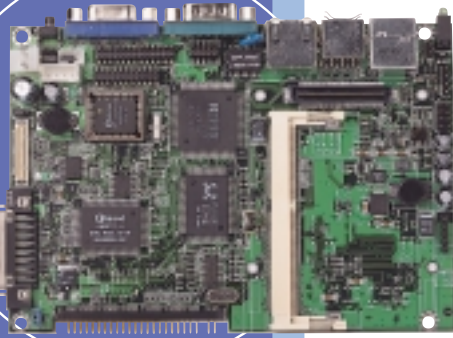


Wafer-5825/5826

Embedded Low power consumption CPU and small form factor solution

FAN Less Embedded CPU with PCMCIA I/F for Internet appliance (Web PAD, Car PC)

12V Only



Wafer-5825

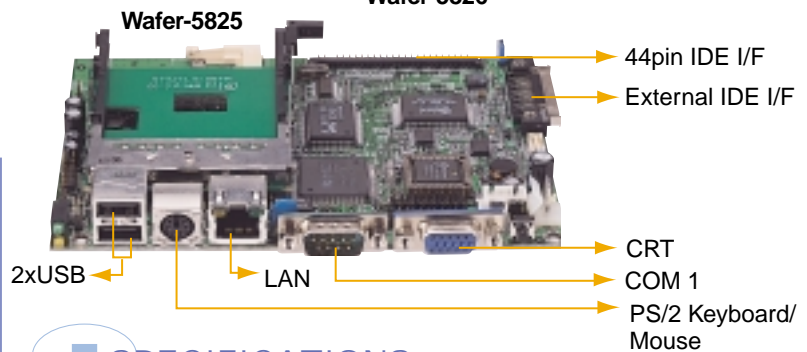
5V Only



Wafer-5826



PCMCIA Kit for Wireless LAN application



IEI is proud to launch Windows CE support on our embedded solution CE 3.0 NOW AVAILABLE (by request)

What is Windows CE?

Windows CE is a compact, scalable and flexible operation system in Microsoft's OS family. Migrating from 2.12 to 3.0 by adding real time feature and more powerful function, it is expected to greatly enhance the system applicability for industry use.

What are the benefits with Windows CE?

Windows CE is specially developed for below purposes:

- 1) Common base for software applications
- 2) Modular design for customization
- 3) Minimize memory footprint and maximize system performance

What are IEI's offerings for customers?

IEI Windows CE dedicate Team provides a complete emulation environment for building CE image by combining either CE 2.12 kernel, CE 3.0 kernel, system drivers and CE-based applications. Customers receive total solutions from IEI including OS licensing, driver support, image build and system testing. In addition we welcome customers' CE inquiry on product software/hardware compatibility, system integration testing and certification.

IEI's embedded systems (NOVA- and Wafer- series) are now ready to support Windows CE. Please contact us for more information.

SPECIFICATIONS

- **CPU:** NS Geode GX1-300MHz
- **BIOS:** Award PnP BIOS
- **System Memory:** up to 512MB (1x 144pin SO-DIMM)
- **Display:** Built-in CS5530A chipset
V-RAM: share with system memory (up to 4MB) setting by BIOS
Resolution: max.1280x1024, 256 colors for CRT 1024x768, 64K for LCD
Connector: external DB-15 for CRT and one internal 31pin LCD connector (DF9, Hirose)
- **I/O:** – 2 x RS-232 (16C550 UARTs compatible)
– 1 x Parallel (SPP/EPP/ECP)
– 2 x USB 1.1
– 1 x IrDA (SIR)
– 1 x IDE channel (1x44 pin header)
– 1 x IDE high-density external connector (wafer-5825)
- **Ethernet:** external RJ-45x1
Realtek RTL8139C 10/100Mbps Ethernet controllers Support WOL function
- **2.0mm pitch floppy port connector (Wafer-5826)**
- **Expansion:** PCMCIA type II socket for PCMCIA daughter board
- **WDT:** software programmable, support 1~ 255 sec. system reset
- **Power connector:** 12V input– 2-pin (3.96mm pitch) (Wafer-5825)
5V input–2-pin (3.96mm pitch) (Wafer-5826)
Molex equivalent SPOX header
- **Power Consumption (with 64MB SDRAM):**
Wafer-5825 – 12V@1A; Wafer-5826 – 5V@1.5A
- **Operating Temperature:** 0-60°C
- **Relative Humidity:** 5~95%, non-condensing
- **Form Factor:** 3.5" disk size Embedded Board
- **Dimensions:** 145 x 102 mm (5.8" x 4")
- **GW:** 700g

Dimensions

